ISO-9001-2015 Certified

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TECHNICAL BULLETIN

TGF-331-2

THERMALLY CONDUCTIVE LIQUID GAP FILLER

TGF-331-2 is a high temperature resistant, liquid gap filler with very high thermal conductivity. It is a heavily filled system with heat conductive metal oxides. The material is a two-component, cured either at room or elevated temperature. The material is an excellent solution for interfacing fragile components. Once cured, it remains a low modulus elastomer designed to assist in relieving CTE stresses during thermal cycling yet maintain enough modulus to prevent pump-out from the interface. TGF-331-2 will only provide only light mechanical adhesion and will not provide structural adhesion to substrates.

TYPICAL PROPERTIES	
Property	**Value**
Color	Blue
Specific Gravity	2.4
Operating Temperature (°C)	-55 – 205
Thermal Conductivity (W/mK)	3.6
Dielectric Strength (V/mil)	275
Dielectric Constant, 1 kHz	8.0
Volume Resistivity, ohm-cm	1.0×10^{14}
Mix Ratio (by volume)	1:1
Mix Ratio (by weight)	100:100
Mixed Viscosity (cps, 25°C)	>500,000
Shelf Life (months)	6
Cure Schedule	16 hours/25°C or 30 min/100°C
Pot Life (minutes)	30
Shore Hardness (A)	5

FOR INDUSTRIAL USE ONLY:

These materials are intended for industrial use only, and the practices of good housekeeping, safety and cleanliness should be followed before, during and after use.

WARNING!

Although the system contains low volatility materials, care should be taken in handling. Adequate ventilation of workplace and ovens is essential. In case of skin contact, wash thoroughly with soap and water. For eyes, flush immediately with plenty of water for at least 10 minutes and seek medical attention. Refer to Safety Data Sheet (SDS) for additional health and safety information.

SHELF LIFE:

The shelf life of these materials is 6 months from the date of manufacture when stored in unopened containers at an average temperature of 25°C.